Amendments to the Specification:

Please amend the paragraph beginning at page 1, line 4, as follows:

-- The invention relates to a cleaning system, ~~cleaning mechanism for an image sensor package,~~ and more particularly to a cleaning system having a combination of a substrate and a frame layer being cleaned by a cleaner ejected slantingly upwards. ~~in particular to a mechanism for efficiently and quickly cleaning an image sensor in package processes, so as to increase the production yield.~~ --

Please amend the paragraphs beginning at page 1, line 21, as follows:

-- In order to finish the above-mentioned package processes, the chamber 24 of the substrate 10 has to be efficiently cleaned so that ~~, so as to decrease~~ the number of particles may be decreased.

Please refer to FIG. 2, ~~is~~ a traditional ~~method of~~ cleaning mechanism for an image sensor package includes a body element 40, a rotating device 42, and a cleaning ~~device~~ mechanism 44.

The body element 40 is formed with a chamber 46. The rotating device 42 is arranged within the chamber 46 of the body element 40. The cleaning ~~device~~ mechanism 44 is arranged within the chamber 46 of the body element 40 and is located on the upper end of the body element 40. ~~So as to while~~When the substrate 10 formed with a frame layer 18 is mounted on the rotating device 42, the chamber 24 of the substrate 10 faces ~~is faced~~ the cleaning mechanism 44. ~~, respectively, the~~ The cleaner of the cleaning mechanism 44 is provided to clean the chamber 46 of the substrate 10.

However, the conventional cleaning mechanism for cleaning an image sensor package has the following drawback. ~~drawbacks.~~

~~1.~~ Since a right angle is formed between the substrate 10 and the frame layer 18, ~~so particle is~~ particles are easily ~~hide in~~hidden at the right angle, ~~thus,~~ and the cleaner can not efficiently clean the chamber 24. --

Please amend the paragraphs beginning at page 2, line 18, as follows:

-- An object of the invention is to provide a cleaning system having a combination of a substrate and a frame layer being cleaned by a cleaner, which is ejected slantingly upwards, so that the combination of the substrate and the frame layer may be cleaned efficiently and the production yield may be increased. ~~cleaning mechanism for an image sensor package, wherein the processes for packaging an image sensor may be efficiently cleaned, so as to increase the production yield.~~

To achieve the above-mentioned object, the invention provides a cleaning system. The cleaning system includes: a combination of a substrate and a frame layer arranged on the substrate to form a chamber together with the substrate; a sealed up body formed with a cleaning room, wherein the substrate is disposed in the cleaning room and fixed to an upper portion of the sealed up body with the chamber facing downwards; and a cleaning mechanism, which is disposed in the cleaning room of the sealed up body, for ejecting a cleaner slantingly upwards to clean the chamber of the combination of the substrate and the frame layer. ~~a cleaning mechanism for an image sensor package, the cleaning mechanism is for cleaning the substrate and the frame layer arranged on the substrate of the image sensor to form a chamber between the frame layer and the substrate. The mechanism includes a seal up body is formed with a cleaning room, the substrate formed with frame layer is fixed on the top end of the cleaning room, then, the chamber is faced down direction of the cleaning room. A rotating device is located within the cleaning room of the seal up body. A cleaning device is mounted on the bottom end of the cleaning room of the seal up body, and is cleaned the chamber of the substrate by cleaner.~~ --

Please amend the paragraphs beginning at page 3, line 13, as follows:

-- FIG. 2 is a schematic ~~illustrated~~ illustration showing a conventional cleaning mechanism for an image sensor package.

FIG. 3 is a schematic ~~illustrated~~ illustration showing a cleaning apparatus ~~mechanism for an image sensor package~~ of the present invention.

FIG. 4 is a cross-sectional view showing a cleaning system ~~mechanism for an image sensor package~~ of the present invention. --

Please amend the paragraphs beginning at page 3, line 20, as follows:

-- Please refer to FIG. 3. A cleaning apparatus ~~mechanism for an image sensor~~ of the present invention includes a sealed up body 50, a cleaning mechanism or cleaning mechanisms 52, and a vacuuming pump 54.

The sealed up body 50 has a lower element 56, a periphery wall 58 connected to the lower element 56, and ~~a upped~~ an upper cover 60 connected to the periphery wall 58 so that a cleaning room 62 is formed. ~~to form a chamber 62.~~

The cleaning mechanism 52 is disposed in ~~device 54 is located within the cleaning room 62 of~~ the sealed up body 50, and ~~mounted on the bottom end of the cleaning room 62 of the seal up body 50,~~ the cleaning mechanism 52 ~~device 54~~ may eject a ~~be ejected the~~ cleaner slantingly upwards. In the embodiment, the cleaner is water, nitrogen or carbon dioxide. ~~or N2 or CO2.~~

The vacuuming pump 54 is located within the cleaning room 62 of the sealed up body 50 to ~~absorb~~ suck the cleaner and particles.

Please refer to FIG. 4, ~~is a cross-sectional schedule showing a cleaning mechanism for an image sensor package.~~ the cleaning system includes a combination of a substrate 64 and a frame layer 66, the sealed up body 50 and the cleaning mechanisms 52. The frame layer 66 is arranged on the substrate 64 to form a chamber 68 together with the substrate 64. ~~A substrate 64 is formed with a frame layer 66 for an image sensor package. A chamber 68 is formed between the substrate 64 and frame layer 66.~~ The substrate 64 is located within the

cleaning room 62, and is mounted on an upper portion 50A ~~the top end~~ of the sealed up body 50 with ~~, then,~~ the chamber 68 facing downwards. ~~is faced down direction of the cleaning device 50.~~ Therefore, the cleaner from the cleaning mechanism 52 ~~device 54~~ is ejected to the chamber 68 so that ~~, so that may be cleaned~~ the chamber 68 may be cleaned by the cleaner, which is ejected slantingly upwards. In this embodiment, the vacuuming pump 54 is disposed in the cleaning room 62 and under the chamber 68 of the combination of the substrate 64 and the frame layer 66 and has a sucking port 55 for sucking the cleaner and the particles. The sucking port 55 is disposed between the two cleaning mechanisms 52, which are disposed in the cleaning room 62 and disposed opposite to each other. --